Vapor Deposition Processes: Protecting Metal Surface

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ABSTRACT:

A group of surface coating methods known as vapor deposition technologies are used to deposit thin layers of materials onto substrates. A solid, liquid, or gas material is converted via these procedures into a vapor phase, which is then condensed onto a substrate to create a thin film. Electronics, optical, aerospace, and automobile industries all frequently use vapor deposition processes to provide coated surfaces with the desired qualities. The principles, varieties, and applications of vapor deposition methods are discussed in this chapter. It emphasizes how crucial precise control over deposition parameters is to achieve the desired film properties and examines the benefits and difficulties of using various approaches. The vapor deposition methods' adaptability and a broad variety of applications in contemporary industrial and technological breakthroughs are also highlighted in the chapter.

KEYWORDS:

Coating, Deposition, Material, Surface, Substrate, Vapour.

I. INTRODUCTION

Many different businesses employ vapor deposition methods to produce thin films or coatings on surfaces. In these procedures, a solid, liquid, or gas is converted into a vapor phase, which is subsequently condensed onto a substrate to create a thin film. Vapor deposition is a flexible technology for producing desired surface properties and functionalities because it allows for exact control over film thickness, composition, and uniformity. Let's delve deeper into the introduction of vapor deposition processes:

PVD, or Physical Vapor Deposition

In the vapor deposition process known as physical vapor deposition, the material is physically transferred from a solid source to a substrate. Evaporation and sputtering are two examples of methods used in PVD processes. In the process of evaporation, a solid substance is heated to produce a vapor that condenses onto the substrate. Highenergy ions are used in the process of sputtering to bombard a target material, ejecting atoms that then fall to the substrate. Metals, alloys, and other materials are frequently deposited using PVD because of their good adhesion, high density, and fine control over film parameters [1], [2].

CVD, or Chemical Vapor Deposition

Chemical vapor deposition is a type of vapor deposition in which precursor gases undergo a chemical reaction that results in the formation of a solid film on the substrate. In CVD, precursor gases are added to a reactor chamber, where they react under carefully regulated circumstances to deposit a thin coating. The subtypes of CVD processes include, among others, atmospheric pressure CVD APCVD, low-pressure CVD LPCVD, and plasma-enhanced CVD PECVD. Materials including metals, ceramics, diamond-like carbon, and semiconductor materials are all commonly deposited via CVD. Excellent film quality, high purity, conformal deposition, and the capacity to deposit intricately accurate structures are among features it offers.

ALD: Atomic Layer Deposition

A specific method of vapor deposition known as atomic layer deposition enables fine control over film composition and thickness at the atomic level. One atomic layer is deposited at a time as a result of the consecutive exposure of a substrate to alternate precursor gases during ALD. The process's inherent self-limitation guarantees exact control over film thickness and homogeneity. ALD is frequently used to deposit thin films with high-quality, conformal coverage, and exact composition control, making it appropriate for usage in advanced material coatings, microelectronics, and nanotechnology. Industries like semiconductor manufacturing,

optics, electronics, solar cells, medical devices, automotive, and aerospace use vapor deposition techniques extensively [3], [4].

These procedures provide benefits like homogeneity, conformal deposition on intricate surfaces, fine control over film characteristics, and the capacity to deposit a large variety of materials. Manufacturers can get specialized surface qualities, improved performance, and expanded functionality for their products and applications by choosing the suitable vapor deposition technique and optimizing process parameters. Vapor deposition technologies are a class of surface coating techniques that are used to deposit very thin layers of materials onto substrates. These processes transform a solid, liquid, or gas material into a vapor phase, which is subsequently condensed onto a substrate to produce a thin film. Vapor deposition techniques are frequently used in the electronic, optical, aerospace, and automotive industries to create coated surfaces with the appropriate properties. In this chapter, the concepts, variations, and applications of vapor deposition technologies are covered.

It focuses on how important precise control over the deposition parameters is to producing the necessary film properties and looks at the advantages and challenges of applying different strategies. The versatility and wide range of uses of vapor deposition techniques in modern industrial and technical advancements are also highlighted in the chapter. Many different sectors use vapor deposition techniques including Physical Vapor Deposition PVD and Chemical Vapor Deposition CVD. These procedures allow for exact control of the thin film deposition on surfaces, enabling the development of coatings with distinctive features. Here are a few typical uses for vapor deposition techniques:

Industry of Semiconductors

For the production of integrated circuits, microprocessors, and other electronic components, vapor deposition methods are widely employed in the semiconductor industry. On silicon wafers, metal and dielectric coatings like silicon dioxide and silicon nitride are deposited using PVD and CVD processes. These films act as insulating, conductive, or passivating layers, allowing for the development of complex circuitry and boosting the functionality and dependability of electronic devices [5], [6].

Glass Coatings

For the creation of optical coatings used in lenses, mirrors, filters, and other optical components, vapor deposition methods are essential. Using PVD or CVD processes, thin films with particular refractive indices and antireflective qualities can be produced onto glass or other substrate materials. These coatings improve optical performance overall, increase light transmission, and minimize glare in devices including cameras, telescopes, eyeglasses, and display technology.

Decorated Surfaces

Many different materials, including metals, polymers, and ceramics, are produced with decorative coatings using vapor deposition methods. Metals like gold, silver, titanium, or chromium can be deposited as thin films on surfaces using PVD processes like sputtering or evaporation. In addition to improving the surface hardness and providing resistance to tarnishing or abrasion, these metallic coatings are aesthetically pleasing. Vapor deposition techniques are utilized to produce decorative finishes that are employed in consumer electronics, jewelry, timepieces, architectural components, and automotive trim.

Protection from Wear and Corrosion

Thin films that offer corrosion protection and wear resistance are made using vapor deposition techniques. To extend the life and enhance the performance of cutting tools, molds, and machine parts, for instance, hard coatings like diamond-like carbon DLC can be applied. Additionally, corrosion-resistant films like titanium nitride or aluminum oxide can be deposited using PVD and CVD processes onto metal substrates used in the chemical processing, aerospace, or maritime industries [7], [8].

Solar Applications and Energy

Production of energy storage devices and thin-film solar cells depends heavily on vapor deposition methods. To make effective solar cells, thin semiconductor layers like amorphous silicon or cadmium telluride can be deposited onto substrates using CVD methods. To improve the performance and stability of energy storage devices, PVD procedures are also utilized to deposit protective coatings over the electrodes or current collectors of these devices.

Applications in Medicine and Biology

Processes for vapor deposition are used in the biomedical and medical industries. For instance, biocompatible coatings can be applied to medical implants using PVD and CVD processes, which improves their compatibility with the body and lowers the chance of rejection. In addition to providing antibacterial qualities, these coatings can improve the functionality and safety of medical devices. These are only a few examples of the numerous uses for vapor deposition techniques. By enabling the production of superior materials, higher performance, and enhanced functionality in a variety of goods and technologies, PVD and CVD processes have become indispensable in a wide range of industries.

II. DISCUSSION

Physical Vapor Deposition

Physical vapor deposition PVD is a class of thin film techniques in which a substance is transformed into the vapor phase in a vacuum chamber and then condensed as an extremely thin layer onto a substrate surface. Metals, plastics, and many other types of coating materials can be applied using PVD metals, ceramics, and other inorganic substances, as well as certain polymers. Glass, metals, and polymers are examples of potential substrates. Therefore, PVD represents a flexible coating technology that may be used with virtually any combination of substrate materials and coating materials. Thin ornamental coatings on plastic and metal objects like trophy cases, toys, pens & pencils, watchcases, and car interior trim are examples of applications for PVD. The coatings are made of clear lacquer-coated thin films of aluminum about 150 nm thick that have a high gloss silver or chrome look. Magnesium fluoride MgF2 antireflection coatings for optical lenses are another application for PVD. In the process of making electronic devices, PVD is mostly used to deposit metal to create electrical connections in integrated circuits. Last but not least, titanium nitride TiN is frequently used in PVD to coat cutting tools and plastic injection molds for wear resistance.

The three steps that make up every physical vapor deposition procedure are: 1 creating the coating vapor, 2 transporting the vapor to the substrate, and 3 condensing the vapors onto the substrate surface. Since the majority of these stages take place inside vacuum chambers, the chamber must be evacuated before beginning the PVD procedure. Any of several techniques, such as electric resistance heating or ion bombardment to evaporate an existing solid or liquid, can be used to create the coating vapor. Numerous PVD processes are the consequence of these and other variants. They are divided into three main categories: vacuum evaporation, sputtering, and ion plating, respectively.

Vacuum Evaporation

Evaporation in a Vacuum by first converting some substances from their solid state to a vapor state in a vacuum, followed by allowing them to condense on the substrate surface, certain substances mainly pure metals can be deposited onto a substrate. The vacuum evaporation setup is as follows: The material that has to be deposited, known as the source, is heated to a temperature where it evaporates or sublimes. The temperature needed for vaporization is substantially lower than what would be needed at atmospheric pressure since heating is done in a vacuum. Additionally, the absence of air in the chamber keeps the source material from oxidizing at the heating temperatures. The substance can be heated and vaporized using several techniques. Before vaporization, a container must be provided to hold the source material. Resistance heating and electron beam bombardment are two crucial vaporization techniques. The simplest type of heating is resistance. The source material is placed inside a container made of a refractory metal like W or Mo. Heating the container with current causes the material it comes into touch with to also become warmer.

The potential for alloying between the holder and its contents, which would cause the deposited layer to become contaminated with the metal of the resistance heating container, is one issue with this heating technique. In electron beam evaporation, a stream of electrons traveling at a high speed is pointed at the surface of the source material to vaporize it. In contrast to resistance heating, which uses a lot of energy, very little energy is used to heat the container, limiting coating contamination of the container material. Whatever the method of vaporization, evaporated atoms leave the source and travel along straight lines until they run into other gas molecules or hit a solid object. The likelihood of collisions between source vapor atoms and other gas molecules is decreased because of the vacuum inside the chamber. The substrate surface that has to be coated is often placed concerning the source so that it will likely be the solid surface where the vapor atoms are deposited. Sometimes the substrate is rotated using a mechanical manipulator to coat all surfaces. The energy level of the impinging atoms is abruptly decreased upon contact with the relatively cool substrate surface to the point that they can no longer continue in a vapor state; they condense and bind to the solid surface, forming a deposited thin layer.

Sputtering

Individual surface atoms may gain enough energy from the impact to be expelled from the surface by transfer of momentum if the surface of a solid or liquid is battered by atomic particles of sufficient high energy. That's the procedure called sputtering. An ionized gas, such as argon, that has been energized utilizing an electric field to form a plasma is the most practical type of high-energy particle. Sputtering is a PVD procedure that includes bombarding the cathodic coating material with argon ions Ar+. This releases surface atoms, which are then deposited onto a substrate to create a thin film on the substrate surface. To promote the bonding of the coating atoms, the substrate must be heated and put close to the cathode. Typical setups include Vacuum evaporation often only works on metals, but sputtering can be used on almost any substance, including alloys, polymers, ceramics, and both metallic and nonmetallic components. Sputtered metals and compounds can be formed into films without affecting their chemical makeup. Reactive gases that combine with the sputtering PVD has a few drawbacks, including 1 slow deposition rates and 2 the presence of trapped gases that can occasionally harm mechanical qualities since the ions attacking the surface are a gas.

Ion Plating

Sputtering and vacuum evaporation are combined in ion plating to create a thin coating on a substrate. The procedure goes like this. In the upper portion of the chamber, the substrate is configured to serve as the cathode, and the source material is put. beneath it. The chamber is then brought to vacuum. Argon gas is introduced, and an electric field is used to ionize it creating Ar+ ions and create a plasma. This causes the substrate to be bombarded by ions sputtering, which scrubs the surface to atomic cleanliness read: very clean. The source material is then heated long enough to produce coating vapors. Resistance heating, electron beam bombardment, and other heating techniques are utilized in a manner reminiscent of vacuum evaporation. The plasma is traversed by the vapor molecules, which then cover the substrate.

Sputtering continues during deposition so that source material ions that have been excited while being exposed to the same energy field as the argon are bombarded as well as the original argon ions. These processing parameters are the result of producing films with a consistent thickness and great substrate adhesion. Due to the scattering effects present in the plasma field, ion plating can be applied to components with irregular geometries. TiN coating on high-speed steel cutting tools like drill bits is an interesting example in this context. Other benefits of the method include coating homogeneity and good adhesion, fast deposition speeds, high film densities, and the ability to coat the interior walls of holes and other hollow structures.

Chemical Vapor Deposition

Physical vapor deposition is a wholly physical method that includes depositing a coating by condensation from the vapor phase onto a substrate. Contrarily, in chemical vapor deposition CVD, a mixture of gases interacts with the surface of a heated substrate to cause the chemical breakdown of some of the gas ingredients and on the substrate, the production of a solid film. An enclosed reaction chamber is where the reactions happen. The coating is created by the reaction producteither a metal or a compoundnucleating and growing on the substrate surface. The majority of CVD processes demand heat. However, other potential energy sources, such as plasma or ultraviolet light, could power the reactions depending on the molecules in question. A wide range of pressures and temperatures are used in CVD, and it can be used on a wide range of substrate and coating materials.

Chemical vapor deposition-based industrial metallurgical methods have been around since the 1800s The focus of contemporary research in CVD is on its coating applications, including coated cemented carbide tools, solar cells, the deposition of refractory metals on jet engine turbine blades, and other applications where resistance to wear, corrosion, erosion, and thermal shock is crucial. Additionally, CVD is a key technology in the creation of integrated circuits. The ability to deposit refractory materials below their melting or sintering temperatures, the ability to control grain size, the fact that the process can be done at atmospheric pressure without the use of vacuum equipment, and the fact that the coating adheres well to the substrate surface are some of the benefits that are frequently cited for CVD. A closed chamber and specific pumping and disposal equipment are typically required because of the corrosive and/or poisonous nature of chemicals. Other drawbacks include the high cost of some reaction ingredients and the generally low material utilization.

Organic Coatings

Organic finishes, commonly referred to as paint coatings or coatings, are frequently used to protect and improve the surfaces of various materials. When applied to a substrate, these coatings, which are primarily polymers, create a protective film. Organic coatings have several advantages, including usefulness, durability, and corrosion resistance. Let's examine some essential features and uses of organic coatings:

Different Organic Coating Types

Coatings made of polymers: The most prevalent kind of organic coatings are those that are based on polymers. They are created by mixing additives, solvents, and pigments with polymers like acrylic, epoxies, polyurethanes, alkyds, or polyesters. Polymer coatings offer superior defense against UV rays, chemicals, weathering, and corrosion.

Dust Coatings: An organic coating that is applied in the form of a dry powder is known as a powder coating. Electrostatically charged powder sticks to the substrate. The material is then heated to cure it, creating a solid, continuous covering. Powder coatings are renowned for their resilience to chipping, scratching, and fading as well as their environmental friendliness low VOC emissions.

Aquatic Coatings: Water serves as the main solvent in water-based organic coatings, often known as waterborne coatings, as opposed to conventional organic solvents. These coatings have benefits including low VOC emissions, less environmental impact, simplicity in use, and quick drying. Architectural paints, furniture coatings, and automotive applications all frequently use water-based coatings.

Uses for Organic Coatings

Defending Coatings: Protecting substrates against corrosion, abrasion, and environmental conditions is one of the main uses of organic coatings. To increase their service life and stop deterioration, these coatings are applied to industrial equipment, machinery, pipelines, automobile parts, and metal structures.

Construction Coatings: In the building sector, organic coatings are frequently employed for architectural purposes. To protect structures against weathering, UV rays, and chemical exposure, they are applied to buildings, bridges, and infrastructure. Architectural coatings offer options for color, texture, and gloss, which further improve the appearance of buildings.

Vehicle Coatings: In the automotive sector, organic coatings are essential for giving vehicles both protection and aesthetic appeal. They are used for basecoats, clearcoats, primers, and specialized coatings like self-healing, scratch-resistant, and anti-corrosion coatings. Automotive coatings provide a polished and appealing appearance along with resistance to mechanical loads, chemicals, and weathering.

Wood Finishes: To preserve and enhance the appearance of wood surfaces, organic coatings are widely employed in the wood industry. These finishes offer resistance to stains, UV rays, scratches, and dampness. To increase the sturdiness, beauty, and lifetime of furniture, floors, cabinets, doors, and other wood products, wood coatings can be applied.

Boat Coatings: In the marine sector, organic coatings are used to prevent corrosion and fouling on ships, boats, offshore constructions, and marine equipment. Marine coatings are made to endure the abrasive conditions, UV radiation, and saltwater exposure seen in hostile marine locations.

Coatings for Packaging: Organic coatings are used to protect, guarantee the integrity of the product, and improve the aesthetic appeal of packaging materials such as metal cans, food containers, and beverage bottles. These coatings provide resistance to moisture, air, light, chemicals, and chemicals, aiding in the preservation and excellent maintenance of the contents. Many different industries use organic coatings to preserve, beautify, and functionally enhance a variety of substrates. The growth and development of organic coating systems are facilitated by the ongoing creation of novel formulations, eco-friendly alternatives, and cutting-edge technologies.

III. CONCLUSION

Surface engineering and coating technologies have undergone a revolution because to vapor deposition procedures like Physical Vapor Deposition PVD and Chemical Vapor Deposition CVD. These procedures provide fine-grained control over the deposition of thin films onto surfaces, enabling the development of coatings with specific functions and physical qualities. In the semiconductor sector, where integrated circuits, microprocessors, and other electronic devices are made, vapor deposition methods have a wide range of uses. Metal and dielectric films can be deposited using PVD and CVD processes, improving the performance, dependability, and compactness of electronic devices. By increasing light transmission, lowering reflection, and enhancing the overall optical performance of lenses, mirrors, filters, and other optical components, optical

coatings benefit from vapor deposition procedures. These coatings are used in display technology, eyewear, telescopes, and cameras. The creation of ornamental finishes also uses vapor deposition methods. Thin metallic coatings can be deposited using PVD processes on a variety of materials, including jewelry, architectural hardware, car trim, and consumer electronics. These coatings offer a pleasing look, a firm surface, and resistance to wear or tarnishing.

REFERENCES

- [1] Y. Yoo, S. H. Park, en J. G. Baek, A Clustering-Based Equipment Condition Model of Chemical Vapor Deposition Process, Int. J. Precis. Eng. Manuf., 2019, doi: 10.1007/s12541-019-00177-y.
- [2] H. Pedersen en S. D. Elliott, Studying chemical vapor deposition processes with theoretical chemistry, Theor. Chem. Acc., 2014, doi: 10.1007/s00214-014-1476-7.
- [3] C. R. Kleijn, R. Dorsman, K. J. Kuijlaars, M. Okkerse, en H. van Santen, Multi-scale modeling of chemical vapor deposition processes for thin film technology, J. Cryst. Growth, 2007, doi: 10.1016/j.jcrysgro.2006.12.062.
- [4] J. Kim, H. P. Kim, M. A. M. Teridi, A. R. B. M. Yusoff, en J. Jang, Bandgap tuning of mixed organic cation utilizing chemical vapor deposition process, Sci. Rep., 2016, doi: 10.1038/srep37378.
- [5] G. Tong et al., Rapid, stable and self-powered perovskite detectors via a fast chemical vapor deposition process, RSC Adv., 2017, doi: 10.1039/c7ra01430a.
- [6] E. S. Pérez, J. S. Pérez, F. M. Piñón, J. M. J. García, O. S. Pérez, en F. J. López, Sequential microcontroller-based control for a chemical vapor deposition process, J. Appl. Res. Technol., 2017, doi: 10.1016/j.jart.2017.07.003.
- [7] X. Li et al., Graphene films with large domain size by a two-step chemical vapor deposition process, Nano Lett., 2010, doi: 10.1021/nl101629g.
- [8] B. S. Thabethe, G. F. Malgas, D. E. Motaung, T. Malwela, en C. J. Arendse, Self-catalytic growth of tin oxide nanowires by chemical vapor deposition process, J. Nanomater., 2013, doi: 10.1155/2013/712361.